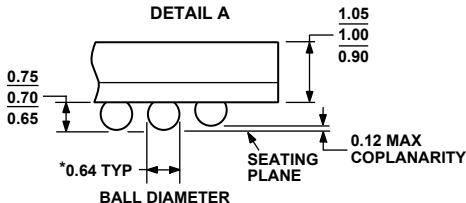
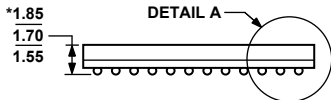
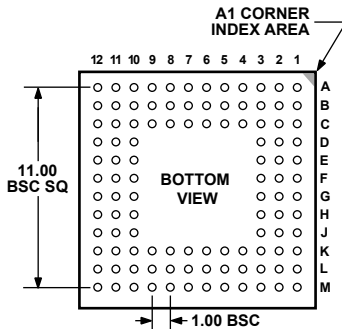
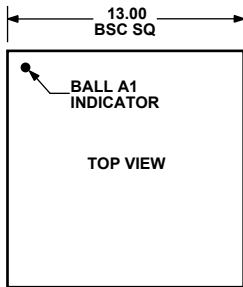


108-Lead Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-108-2)

Dimensions shown in millimeters

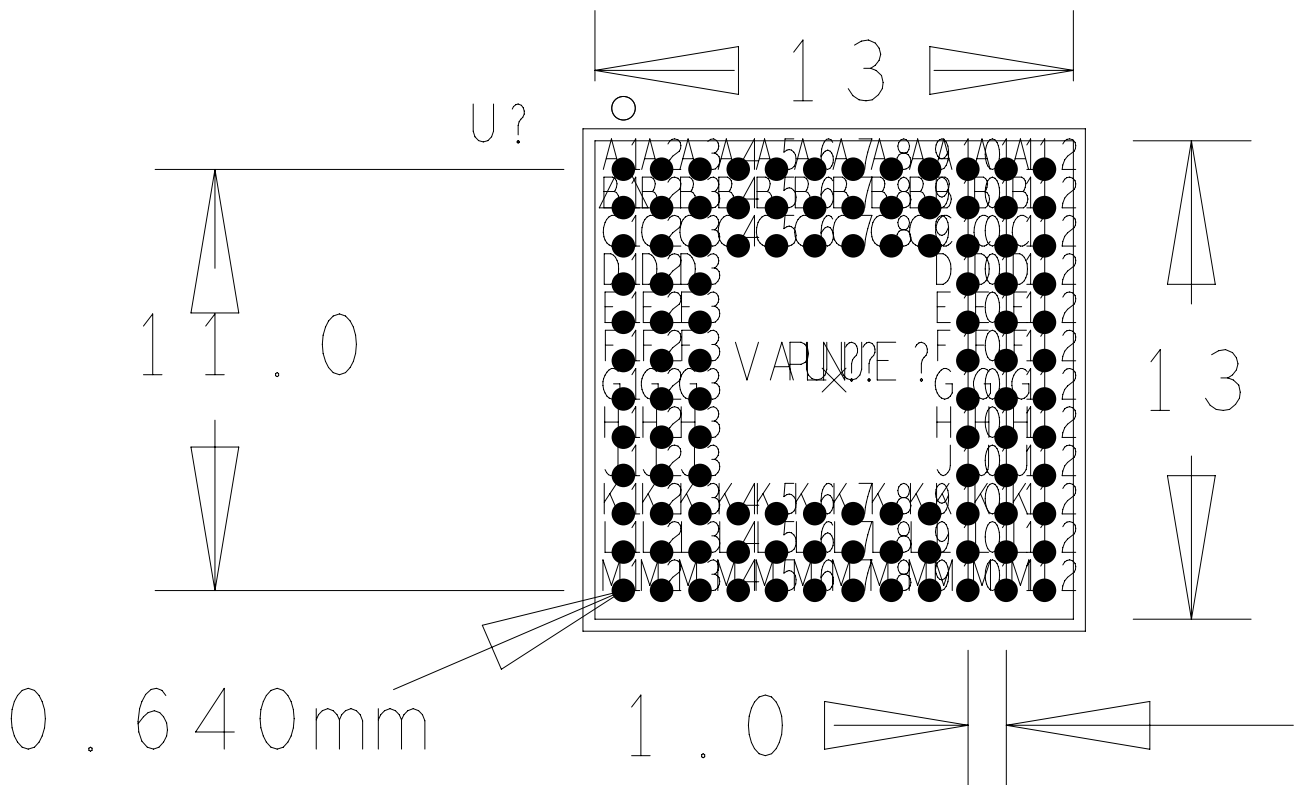


*COMPLIANT WITH JEDEC STANDARDS MO-192-AAD-1 WITH
THE EXCEPTION OF PACKAGE HEIGHT AND BALL DIAMETER.

Analog Devices

BC-108-2

REV A



(Dim . are in MM)

LAST MODIFIED 06/07/07